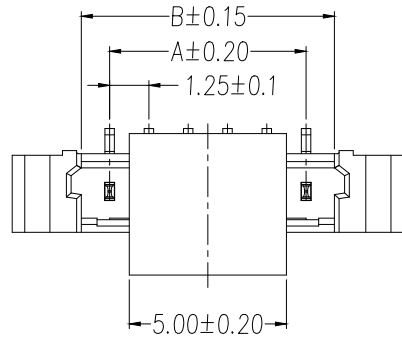


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



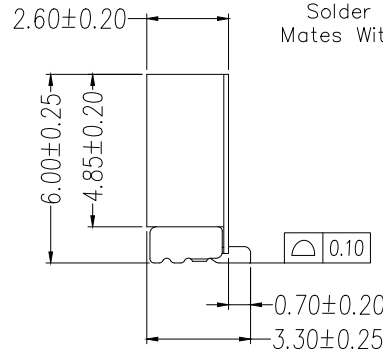
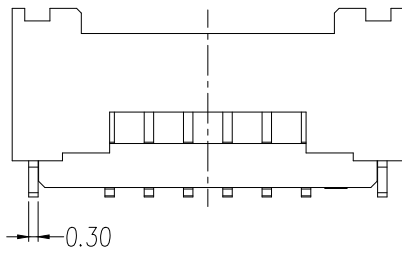
SPECIFICATIONS

Electrical

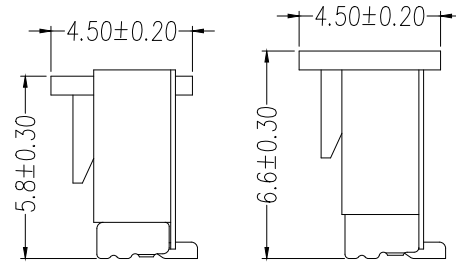
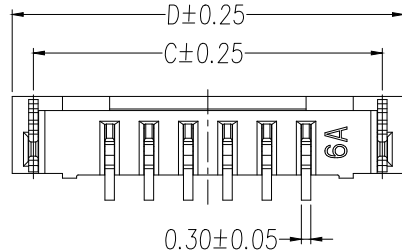
Current Rating: 1A AC/DC
 Voltage Rating: 150V AC/DC
 Contact Resistance: ≤20mΩ
 Insulation Resistance: 500 MΩ MIN
 Withstanding Voltage: 500V AC/minute
 Temperature Range-Operating: -40°C~+105°C

Material

Housing: LCP (UL94V-0), Natural
 Cap: LCP (UL94V-0), Natural
 Terminal: Copper Alloy, Tin-Plated
 Solder Tab: Copper Alloy, Tin-Plated
 Mates With Housing: FHG12510 Series



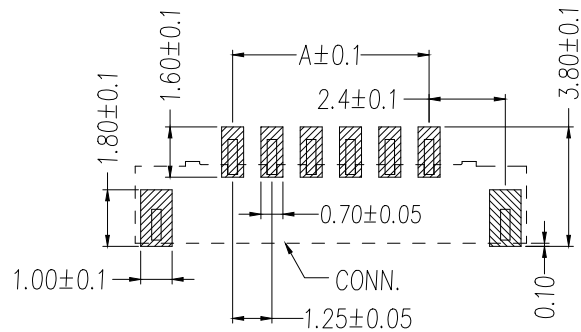
Circuits (n)	Part NO.	Dimensions			
		A	B	C	D
2	FWF12523-S02S23NAM	1.25	3.05	6.10	7.45
3	FWF12523-S03S23NAM	2.50	4.30	7.35	8.70
4	FWF12523-S04S23NAM	3.75	5.55	8.60	9.95
5	FWF12523-S05S23NAM	5.00	6.80	9.85	11.20
6	FWF12523-S06S23NAM	6.25	8.05	11.10	12.45
7	FWF12523-S07S23NAM	7.50	9.30	12.35	13.70
8	FWF12523-S08S23NAM	8.75	10.55	13.60	14.95
9	FWF12523-S09S23NAM	10.00	11.80	14.85	16.20
10	FWF12523-S10S23NAM	11.25	13.05	16.10	17.45
11	FWF12523-S11S23NAM	12.50	14.30	17.35	18.70
12	FWF12523-S12S23NAM	13.75	15.55	18.60	19.95
13	FWF12523-S13S23NAM	15.00	16.80	19.85	21.20
14	FWF12523-S14S23NAM	16.25	18.05	21.10	22.45
15	FWF12523-S15S23NAM	17.50	19.30	22.35	23.70
16	FWF12523-S16S23NAM	18.75	20.55	23.60	24.95



Ordering Information

FWF 125 23 - S XX S 2 3 NA M
 1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 125-Pitch1.25mm	3 Distinction No. 23	4 Row Option S-Single row	5 Circuits XX
6 Entry Angle S-180° Vertical	7 Plating 2-Tin Plated	8 Material-Resin 3-LCP	9 Color-Resin NA-Natural	10 Packaging M-Reel

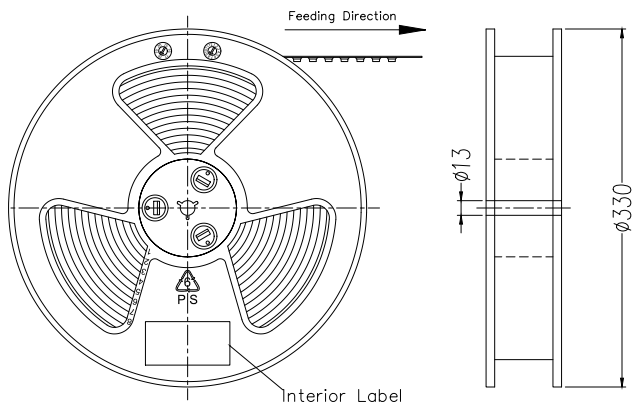


Recommended P.C.Board Layout

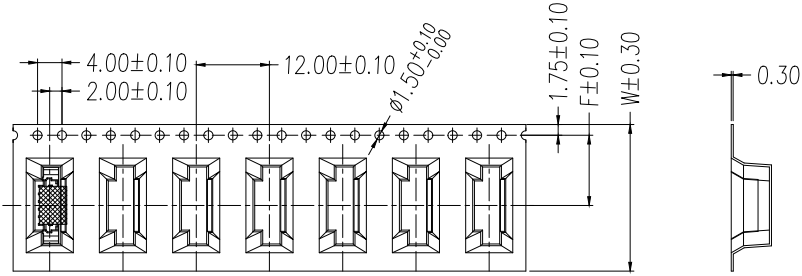
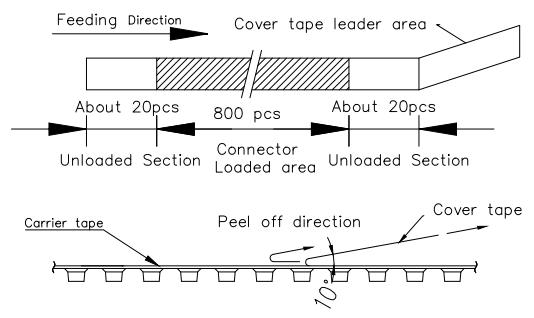
 THIRD ANGLE PROJECTION DESIGN UNITS mm SCALE 5:1 SIZE A4	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 26/OCT/21	PART NO. FWF12523-SXXS23NAM	ITEM NO. FWF12523	 Building Technology Cornerstone REV 0 SHEET NO. 1/2
	X. ±0.30	X.* ±5'	CHECKED BY GISELLE	DATE 26/OCT/21	TITLE Wire to Board Pitch 1.25mm(Wafer)		
	X.X ±0.20	X.X' ±2'	DRAWN BY PYD	DATE 26/OCT/21	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	X.XX ±0.15	X.XX' ±1'					

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A
B
C
D
E
F

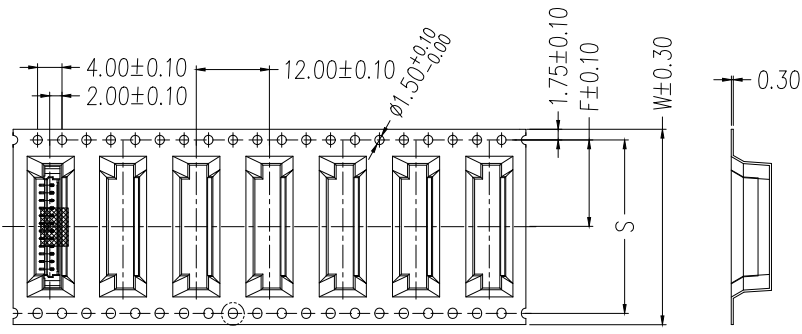


- 10 sprocket hole cumulative tolerance±0.2
- Carrier camber is within 1.0mm in 250mm
- Material: Clear conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Peel off force of cover tape & carrier tape: 20g~130g (0.2N~1.3N)
- Component load per 13" reel: 800 pcs

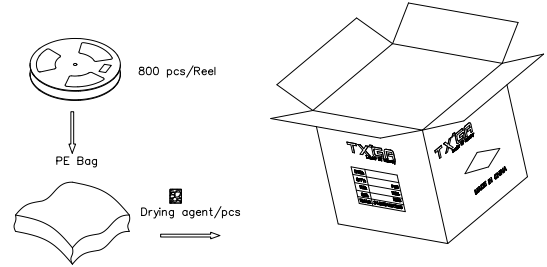


Circuits: 2~8

Circuits (n)	Dimensions		
	W	S	F
2~8	24	—	11.5
9~12	32	28.4	14.2
13~16	44	40.4	20.2



Circuits: 9~16



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone	
	X. ±0.30	X.* ±5'	LEO	26/OCT/21	FWF12523-SXXS23NAM	FWF12523		
	DESIGN UNITS	X.X ±0.20	X.X' ±2'	CHECKED BY	DATE	TITLE		REV 0 SHEET NO. 2/2
	mm	X.XX ±0.15	X.XX' ±1'	GISELLE	26/OCT/21	Wire to Board Pitch 1.25mm(Wafer)		
SCALE	SIZE	X.XXX ±0.10	X.XXX' ±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
5:1	A4			PYD	26/OCT/21			